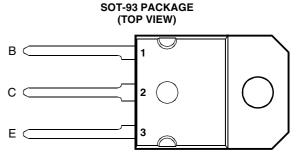
BOURNS®

- **Designed for Complementary Use with the BD746 Series**
- 115 W at 25°C Case Temperature
- 20 A Continuous Collector Current
- 25 A Peak Collector Current
- **Customer-Specified Selections Available**



Pin 2 is in electrical contact with the mounting base.

MDTRAAA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT		
	BD745		50		
Collector-base voltage (I _E = 0)	BD745A	V	70	V	
	BD745B	V _{CBO}	90	V	
	BD745C		110		
	BD745		45		
Collector-emitter voltage (I _B = 0)	BD745A	V	60	V	
	BD745B	V _{CEO}	80	V	
	BD745C		100		
Emitter-base voltage	V _{EBO}	5	V		
Continuous collector current	I _C	20	Α		
Peak collector current (see Note 1)	I _{CM}	25	Α		
Continuous base current	I _B	7	Α		
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)	P _{tot}	115	W		
Continuous device dissipation at (or below) 25°C free air temperature (see Note	P _{tot}	3.5	W		
Unclamped inductive load energy (see Note 4)	½Ll _C ²	90	mJ		
Operating free air temperature range			-65 to +150	°C	
Operating junction temperature range	T _j	-65 to +150	°C		
Storage temperature range	T _{stg}	-65 to +150	°C		
Lead temperature 3.2 mm from case for 10 seconds	T _L	260	°C		

- NOTES: 1. This value applies for $t_p \le 0.3$ ms, duty cycle $\le 10\%$. 2. Derate linearly to 150°C case temperature at the rate of 0.92 W/°C.
 - 3. Derate linearly to 150°C free air temperature at the rate of 28 mW/°C.
 - 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, $I_{B(on)}$ = 0.4 A, R_{BE} = 100 Ω , $V_{BE(off)} = 0$, $R_S = 0.1 \Omega$, $V_{CC} = 20 V$.



electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = 30 mA	I _B = 0	(see Note 5)	BD745 BD745A BD745B BD745C	45 60 80 100			V
I _{CBO}	Collector cut-off current	$V_{CE} = 90 \text{ V}$ $V_{CE} = 110 \text{ V}$ $V_{CE} = 50 \text{ V}$ $V_{CE} = 70 \text{ V}$ $V_{CE} = 90 \text{ V}$ $V_{CE} = 110 \text{ V}$	$V_{BE} = 0$	$T_{C} = 125^{\circ}C$ $T_{C} = 125^{\circ}C$ $T_{C} = 125^{\circ}C$ $T_{C} = 125^{\circ}C$	BD745 BD745A BD745B BD745C BD745 BD745A BD745B BD745C			0.1 0.1 0.1 0.1 5 5 5	mA
I _{CEO}	Collector cut-off current	$V_{CE} = 30 \text{ V}$ $V_{CE} = 60 \text{ V}$	$I_{B} = 0$ $I_{B} = 0$		BD745/745A BD745B/745C			0.1 0.1	mA
I _{EBO}	Emitter cut-off current	V _{EB} = 5 V	I _C = 0					0.5	mA
h _{FE}	Forward current transfer ratio	$V_{CE} = 4 V$ $V_{CE} = 4 V$ $V_{CE} = 4 V$	$I_C = 5 A$	(see Notes 5 a	nd 6)	40 20 5		150	
V _{CE(sat)}	Collector-emitter saturation voltage	$I_{B} = 0.5 A$ $I_{B} = 5 A$	$I_C = 5 A$ $I_C = 20 A$	(see Notes 5 and 6)				1 3	V
V_{BE}	Base-emitter voltage	$V_{CE} = 4 V$ $V_{CE} = 4 V$	$I_C = 5 A$ $I_C = 20 A$	(see Notes 5 and 6)				1	V
h _{fe}	Small signal forward current transfer ratio	V _{CE} = 10 V	I _C = 1 A	f = 1 kHz		25			
h _{fe}	Small signal forward current transfer ratio	V _{CE} = 10 V	I _C = 1 A	f = 1 MHz		5			

NOTES: 5. These parameters must be measured using pulse techniques, t_p = 300 μ s, duty cycle \leq 2%.

thermal characteristics

PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.1	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			35.7	°C/W

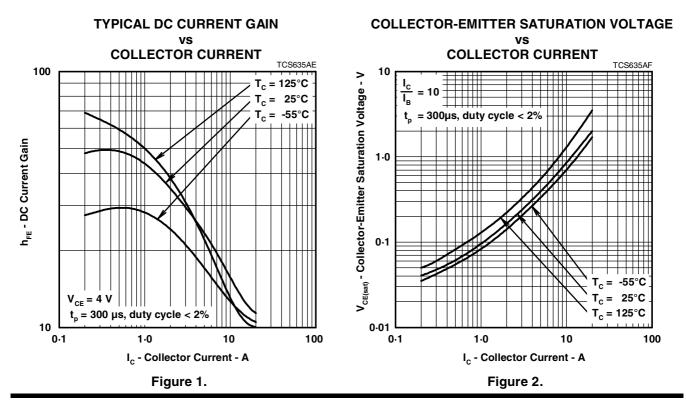
resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
t _d	Delay time					20		ns
t _r	Rise time	I _C = 5 A	$I_{B(on)} = 0.5 A$	$I_{B(off)} = -0.5 A$		350		ns
t _s	Storage time	$V_{BE(off)} = -4.2 \text{ V}$	$R_L = 6 \Omega$	$t_p = 20 \mu s, dc \le 2\%$		500		ns
t _f	Fall time					400		ns

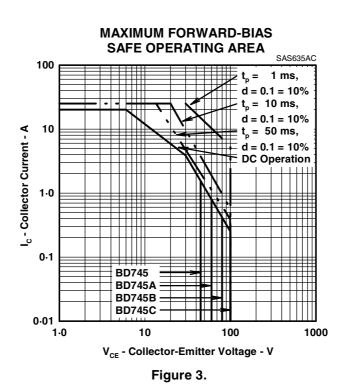
 $[\]begin{tabular}{ll} \dagger Voltage and current values shown are nominal; exact values vary slightly with transistor parameters. \end{tabular}$

^{6.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

TYPICAL CHARACTERISTICS



MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION

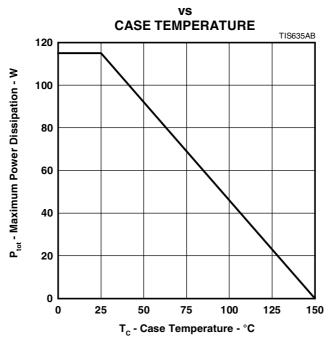


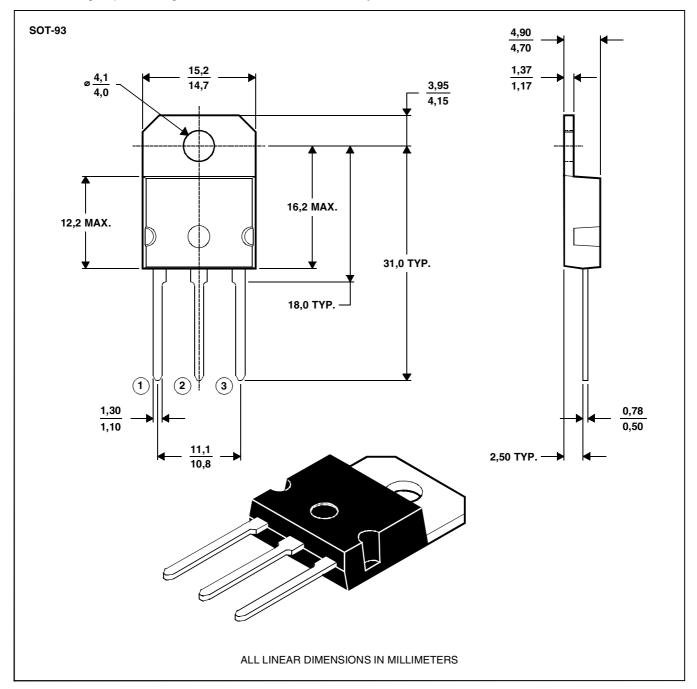
Figure 4.

MECHANICAL DATA

SOT-93

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

MDXXAW